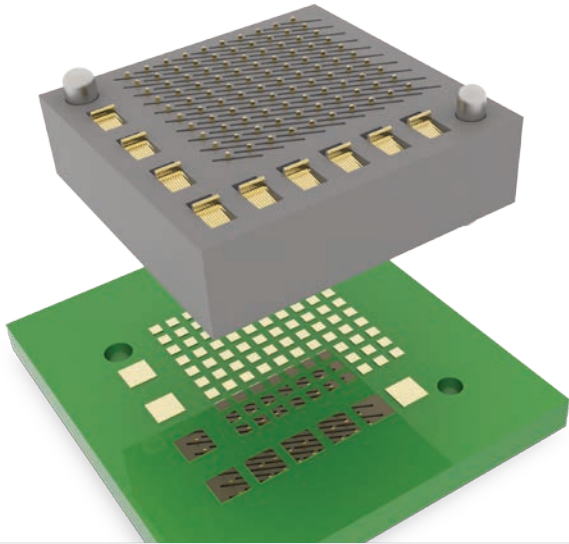




0.05" 1.27mm Vertical Compression (Z-Axis) LGA Connector



RZ is a high-density, solderless, open-field, vertically-compressed connector utilizing a patented z-axis contact system configured for between-boards compression applications.

Features & Benefits

- 20 to 175 contacts
- Compression interface
- Land Grid Array (LGA), solderless technology
- Low-volume production
- Molded & laser-machined versions
- Rectangular versions with various pin count & pin height options available
- Unique shapes



Materials

ContactBeCu C17200 per ASTM B194 (brush alloy 190)
Contact FinishGold per ASTM B488 over nickel per SAE AMS-QQ-N-290
Molded InsulatorGlass-filled polyphenylene sulfide (PPS) per MIL-M-24519
HardwareStainless steel per ASTM A582/582M, Passivated per SAE AMS-2700

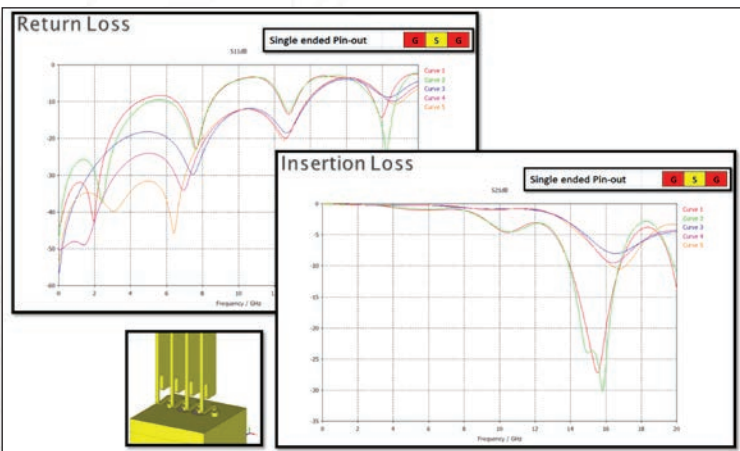
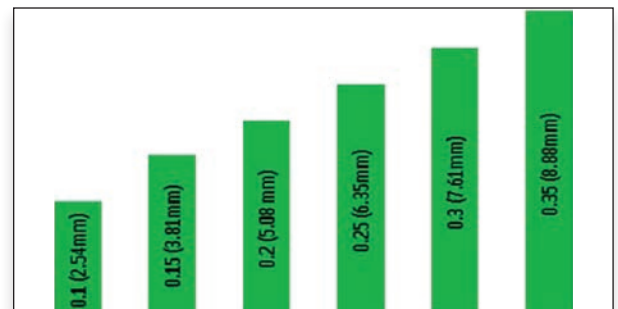
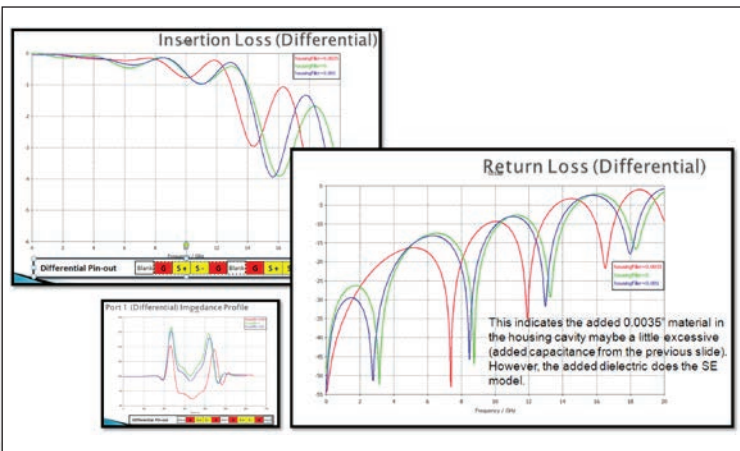
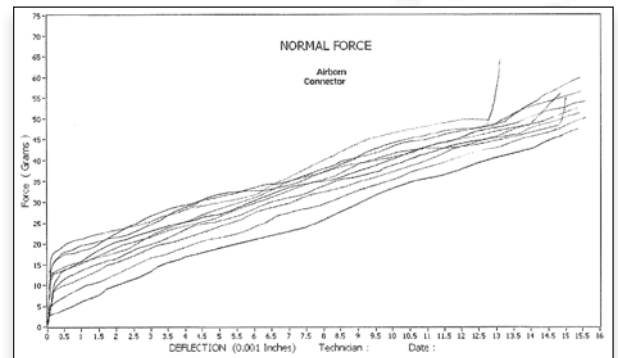
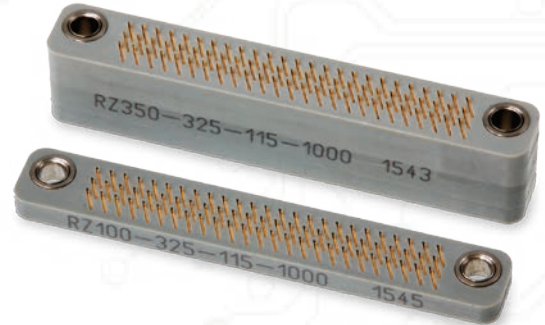
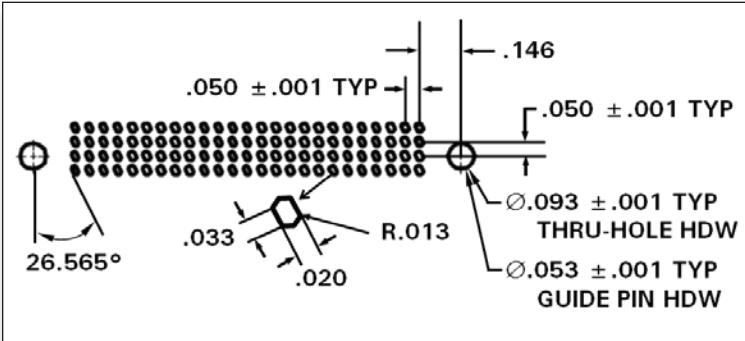
Performance

Contact Compression-0.01"/side (nominal) for 0.100" and 0.150" connector heights;-0.015"/side (nominal) for 0.200", 0.250", 0.300" and 0.350"connector heights
Compression ForceAt a nom. of 0.01, compression force is 30 to 40 grams; At a nom. of 0.015, compression force is 40 to 50 grams
Contact Co-Planarity0.006 max
Contact Wipe0.007" for 0.100" and 0.150" connector heights; 0.015" for 0.200", 0.250", 0.300" and 0.350" connector heights
Current Rating0.5 amperes
Contact Resistance25 milliohms typical (contact height dependent)
Operating Temperature-65° C to +125° C
Insulation Resistance5,000 megaohms minimum @ 100 VDC
Dielectric Withstanding Voltage250 VDC @ sea level, 100 VDC @ 70,000 ft.
DurabilityMin.50 mating cycles – currently testing for 1000 cycles

RZB-C



Typical 0.750" Stack Height SI Performance — Both SE & DIF



	10 pin / Row	15 pin / Row	20 pin / Row	25 pin / Row
2 Row	X	X	X	X
3 Row	X	X	X	X
4 Row	X	X	X	X
5 Row	X	X	X	X
6 Row	X	X	X	X
7 Row	X	X	X	X

Single-Ended S-Parameters

Total Number of Pins Offering

